

27C256

256K (32K x 8) CMOS EPROM

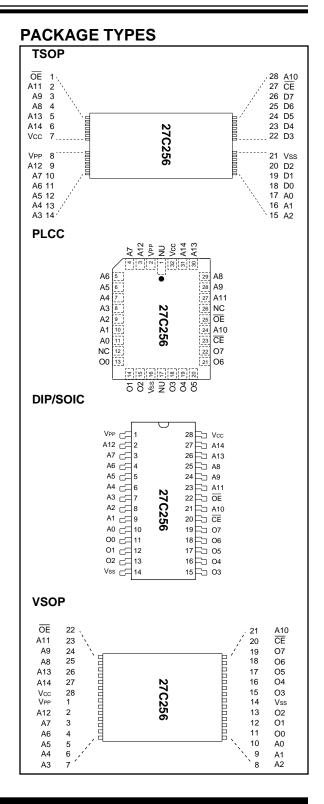
FEATURES

- High speed performance
 - 90 ns access time available
- CMOS Technology for low power consumption
 - 20 mA Active current
 - 100 µA Standby current
- · Factory programming available
- · Auto-insertion-compatible plastic packages
- · Auto ID aids automated programming
- · Separate chip enable and output enable controls
- High speed "express" programming algorithm
- Organized 32K x 8: JEDEC standard pinouts
 - 28-pin Dual-in-line package
 - 32-pin PLCC Package
 - 28-pin SOIC package
 - 28-pin Thin Small Outline Package (TSOP)
 - 28-pin Very Small Outline Package (VSOP)
 - Tape and reel
- Data Retention > 200 years
- Available for the following temperature ranges:
 - Commercial: 0°C to +70°C
 - Industrial: -40°C to +85°C
 - Automotive: -40°C to +125°C

DESCRIPTION

The Microchip Technology Inc. 27C256 is a CMOS 256K bit electrically Programmable Read Only Memory (EPROM). The device is organized as 32K words by 8 bits (32K bytes). Accessing individual bytes from an address transition or from power-up (chip enable pin going low) is accomplished in less than 90 ns. This very high speed device allows the most sophisticated micro-processors to run at full speed without the need for WAIT states. CMOS design and processing enables this part to be used in systems where reduced power consumption and reliability are requirements.

A complete family of packages is offered to provide the most flexibility in applications. For surface mount applications, PLCC, SOIC, VSOP or TSOP packaging is available. Tape and reel packaging is also available for PLCC or SOIC packages.



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1.0 ELECTRICAL CHARACTERISTICS

1.1 <u>Maximum Ratings*</u>

Vcc and input voltages w.r.t. Vss......-0.6V to +7.25V

VPP voltage w.r.t. VSS during	
programming	0.6V to +14.0V
Voltage on A9 w.r.t. Vss	0.6V to +13.5V
Output voltage w.r.t. Vss	-0.6V to Vcc +1.0V
Storage temperature	65°C to +150°C
Ambient temp. with power applied .	65°C to +125°C

*Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: PIN FUNCTION TABLE

Name	Function
A0-A14	Address Inputs
CE	Chip Enable
ŌĒ	Output Enable
Vpp	Programming Voltage
00 - 07	Data Output
Vcc	+5V Power Supply
Vss	Ground
NC	No Connection; No Internal Connec- tion
NU	Not Used; No External Connection Is Allowed

			:C = +5V (ommercial dustrial: tended (A	Famb = 0°C to +70°C Famb = -40°C to +85°C Famb = -40°C to +125°C			
Parameter	Part*	Status	Symbol	Min.	Max.	Units	Conditions
Input Voltages	all	Logic "1" Logic "0"	Vih Vil	2.0 -0.5	Vcc+1 0.8	V V	
Input Leakage	all	_	ILI	-10	10	μA	VIN = 0 to VCC
Output Voltages	all	Logic "1" Logic "0"	Voh Vol	2.4	0.45	V V	IOH = -400 μA IOL = 2.1 mA
Output Leakage	all		Ilo	-10	10	μA	VOUT = 0V to VCC
Input Capacitance	all	_	CIN	_	6	pF	Vin = 0V; Tamb = 25°C; f = 1 MHz
Output Capacitance	all	_	Соит	_	12	pF	Vo∪⊤ = 0V; Tamb = 25°C; f = 1 MHz
Power Supply Current, Active	C I,E	TTL input TTL input	ICC1 ICC2		20 25	mA mA	$\label{eq:VCC} \begin{array}{l} VCC = 5.5V; \ VPP = VCC \\ f = 1 \ MHz; \\ \overline{OE} = \overline{CE} = VIL; \\ IOUT = 0 \ mA; \\ VIL = -0.1 \ to \ 0.8V; \\ VIH = 2.0 \ to \ VCC; \\ Note 1 \end{array}$
Power Supply Current, Standby	C I, E all	TTL input TTL input CMOS input	Icc(s)		2 3 100	mA mA μA	<u>CE</u> = Vcc ± 0.2V
IPP Read Current VPP Read Voltage	all all	Read Mode Read Mode	Ipp Vpp	Vcc-0.7	100 Vcc	μA V	Vpp = 5.5V

TABLE 1-2: READ OPERATION DC CHARACTERISTICS

* Parts: C=Commercial Temperature Range; I, E=Industrial and Extended Temperature Ranges

Note 1: Typical active current increases .75 mA per MHz up to operating frequency for all temperature ranges.

TABLE 1-3: READ OPERATION AC CHARACTERISTICS

AC Testing Waveform: Output Load: Input Rise and Fall Times Ambient Temperature:							$V_{IH} = 2.4V$ and $V_{IL} = 0.45V$; $V_{OH} = 2.0V$ $V_{OL} = 0.8V$ 1 TTL Load + 100 pF s: 10 ns Commercial: Tamb = 0°C to +70°C Industrial: Automotive: Tamb = -40°C to +125°C						+70°C +85°C
Denemerten	C 1	27C2	56-90*	27C2	56-10*	27C2	256-12	27C2	56-15	27C256-20			Conditions
Parameter	Sym	Min	Max	Min	Max	Min	Max	Min	Max	Min	Мах	Units	Conditions
Address to Output Delay	tACC	_	90	_	100		120	_	150		200	ns	CE=OE =VIL
CE to Output Delay	tCE	_	90		100		120	—	150	_	200	ns	$\overline{OE} = VIL$
OE to Output Delay	tOE	_	40		45		55	_	65		75	ns	$\overline{CE} = VIL$
CE or OE to O/P High Impedance	tOFF	0	30	0	30	0	35	0	50	0	55	ns	
Output Hold from Address CE or OE, whichever goes first	tOH	0		0		0	_	0	_	0	_	ns	

* -10, -90 AC Testing Waveform: VIH = 2.4V and VIL = .45V; VOH = 1.5V and VOL = 1.5V Output Load: 1 TTL Load + 30pF

Output Load: 1 TTL Load + 30pF

FIGURE 1-1: READ WAVEFORMS

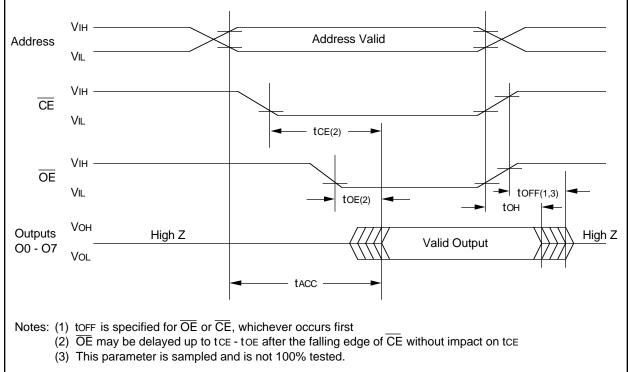


TABLE 1-4: PROGRAMMING DC CHARACTERISTICS

	Ambient Temperature: Tamb = $25^{\circ}C \pm 5^{\circ}C$ VCC = $6.5V \pm 0.25V$, VPP = VH = $13.0V \pm 0.25V$									
Parameter	Status	Symbol	Min	Max.	Units	Conditions				
Input Voltages	Logic"1" Logic"0"	Vih Vi∟	2.0 -0.1	Vcc+1 0.8	V V					
Input Leakage	—	Iц	-10	10	μΑ	VIN = 0V to VCC				
Output Voltages	Logic"1" Logic"0"	Vон Vol	2.4	0.45	V V	IOH = -400 μA IOL = 2.1 mA				
Vcc Current, program & verify		ICC2		20	mA	Note 1				
VPP Current, program	—	IPP2	_	25	mA	Note 1				
A9 Product Identification		Vн	11.5	12.5	V					

Note 1: VCC must be applied simultaneously or before VPP and removed simultaneously or after VPP

TABLE 1-5: PROGRAMMING AC CHARACTERISTICS

for Program, Program Verify and Program Inhibit ModesAC Testing Waveform: Utput Load:VIH=2.4V and VIL=0.45V; VOH=2.0V; VOL=0.8V 1 TTL Load + 100pF Ambient Temperature: Tamb=25°C ± 5°C VCC= 6.5V ± 0.25V, VPP = VH = 13.0V ± 0.25V										
Parameter		Symbol	Min.	Max.	Units	Remarks				
Address Set-Up Time		tAS	2		μs					
Data Set-Up Time	tDS	2	_	μs						
Data Hold Time		tDH	2	_	μs					
Address Hold Time		tAH	0	_	μs					
Float Delay (2)		tDF	0	130	ns					
Vcc Set-Up Time		tvcs	2	—	μs					
Program Pulse Width (1)		tPW	95	105	μs	100 μs typical				
CE Set-Up Time		tCES	2	_	μs					
OE Set-Up Time		tOES	2	—	μs					
VPP Set-Up Time		tVPS	2	_	μs					
Data Valid from OE		tOE	_	100	ns					

Note 1: For express algorithm, initial programming width tolerance is 100 μ s ±5%.

2: This parameter is only sampled and not 100% tested. Output float is defined as the point where data is no longer driven (see timing diagram).

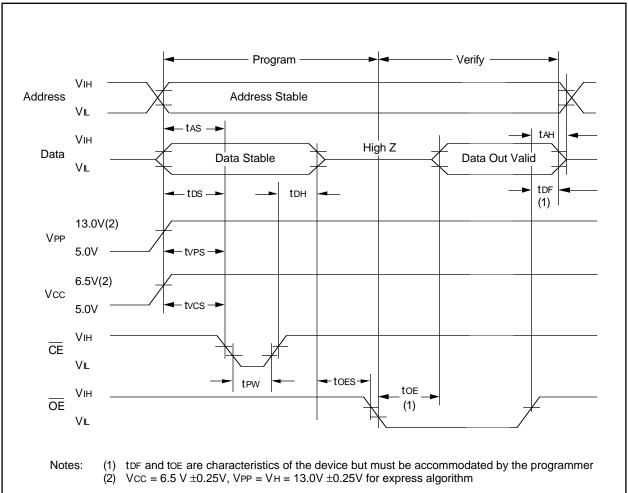


FIGURE 1-2: PROGRAMMING WAVEFORMS

TABLE 1-6: MODES

Operation Mode	CE	OE	VPP	A9	00 - 07
Read	VIL	VIL	Vcc	Х	Dout
Program	VIL	Vін	Vн	Х	DIN
Program Verify	Viн	VIL	Vн	Х	Dout
Program Inhibit	Viн	Vін	Vн	Х	High Z
Standby	Viн	Х	Vcc	Х	High Z
Output Disable	VIL	Vін	Vcc	Х	High Z
Identity	VIL	VIL	Vcc	Vн	Identity Code

X = Don't Care

1.2 <u>Read Mode</u>

(See Timing Diagrams and AC Characteristics)

Read Mode is accessed when:

- a) the \overline{CE} pin is low to power up (enable) the chip
- b) the $\overline{\text{OE}}$ pin is low to gate the data to the output pins

For Read operations, if the addresses are stable, the address access time (tACC) is equal to the delay from \overline{CE} to output (tCE). Data is transferred to the output after a delay from the falling edge of \overline{OE} (tOE).

1.3 Standby Mode

The standby mode is defined when the \overline{CE} pin is high (VIH) and a program mode is not defined.

When these conditions are met, the supply current will drop from 20 mA to 100 $\mu A.$

1.4 Output Enable

This feature eliminates bus contention in multiple bus microprocessor systems and the outputs go to a high impedance when the following condition is true:

• The OE pin is high and the program mode is not defined.

1.5 Erase Mode (U.V. Windowed Versions)

Windowed products offer the ability to erase the memory array. The memory matrix is erased to the all 1's state when exposed to ultraviolet light. To ensure complete erasure, a dose of 15 watt-second/cm² is required. This means that the device window must be placed within one inch and directly underneath an ultraviolet lamp with a wavelength of 2537 Angstroms, intensity of 12,000 μ W/cm² for approximately 20 minutes.

1.6 Programming Mode

The Express Algorithm has been developed to improve on the programming throughput times in a production environment. Up to ten 100-microsecond pulses are applied until the byte is verified. No overprogramming is required. A flowchart of the express algorithm is shown in Figure 1-3.

Programming takes place when:

- a) Vcc is brought to the proper voltage,
- b) VPP is brought to the proper VH level,
- c) the \overline{OE} pin is high, and
- d) the \overline{CE} pin is low.

Since the erased state is "1" in the array, programming of "0" is required. The address to be programmed is set via pins A0-A14 and the data to be programmed is presented to pins O0-O7. When data and address are stable, a low going pulse on the \overline{CE} line programs that location.

1.7 <u>Verify</u>

After the array has been programmed it must be verified to ensure all the bits have been correctly programmed. This mode is entered when all the following conditions are met:

- a) Vcc is at the proper level,
- b) VPP is at the proper VH level,
- c) the \overline{CE} line is high, and
- d) the \overline{OE} line is low.

1.8 Inhibit

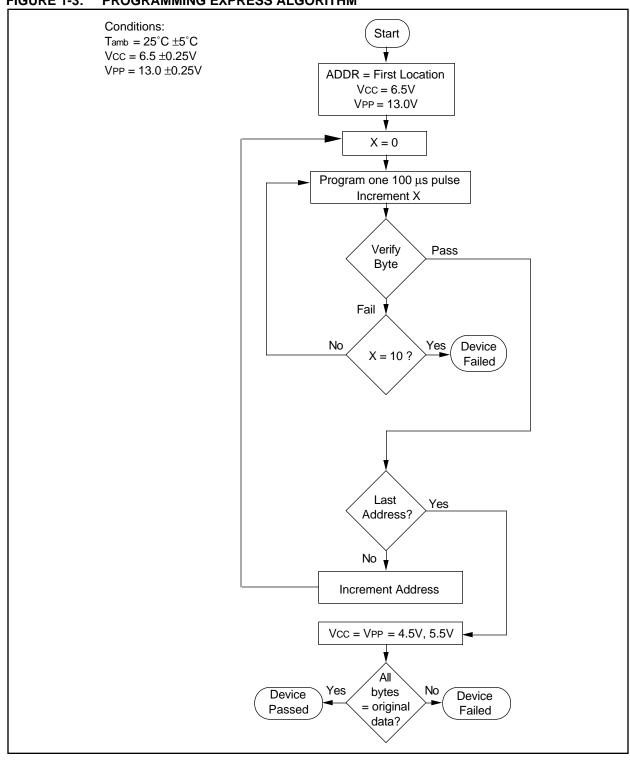
When programming multiple devices in parallel with different data, only \overline{CE} need be under separate control to each device. By pulsing the \overline{CE} line low on a particular device, that device will be programmed; all other devices with \overline{CE} held high will not be programmed with the data, although address and data will be available on their input pins.

1.9 Identity Mode

In this mode specific data is output which identifies the manufacturer as Microchip Technology Inc. and device type. This mode is entered when Pin A9 is taken to VH (11.5V to 12.5V). The \overline{CE} and \overline{OE} lines must be at VIL. A0 is used to access any of the two non-erasable bytes whose data appears on O0 through O7.

Pin 👝	Input	Output								
Identity	A0	0 7	0 6	0 5	0 4	0 3	0 2	0 1	0 0	Hex
Manufacturer Device Type*	VIL VIH	0 1	0 0	1 0	0 0	1 1	0 1	0 0	1 0	29 8C

* Code subject to change



NOTES:

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NOTES:

27C256 Product Identification System

To order or to obtain information (e.g., on pricing or delivery), please use listed part numbers, and refer to factory or listed sales offices.

27C	256 – 90	I /TS				
		T	Package:	P SO TS	= = =	Plastic Leaded Chip Carrier Plastic DIP (Mil 600) Plastic SOIC (Mil 300) Thin Small Outline Package (TSOP) 8x20mm Very Small Outline Package (VSOP) 8x13.4mm
			Temperature Range:	Ι	=	0°C to +70°C -40°C to +85°C -40°C to +125°C
			Access	90	=	90 ns
			Time:	10	=	100 ns
				12	=	120 ns
				15	=	150 ns
				20	=	200 ns
			——– Device	27C256		256K (32K x 8) CMOS EPROM

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Corporate Office

Microchip Technology Inc. 2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 602 786-7200 Fax: 602 786-7277 Technical Support: 602 786-7627 Web: http://www.microchip.com

Atlanta

Microchip Technology Inc. 500 Sugar Mill Road, Suite 200B Atlanta, GA 30350 Tel: 770 640-0034 Fax: 770 640-0307

Boston

Microchip Technology Inc. 5 Mount Royal Avenue Marlborough, MA 01752 Tel: 508 480-9990 Fax: 508 480-8575

Chicago

Microchip Technology Inc. 333 Pierce Road, Suite 180 Itasca, IL 60143 Tel: 708 285-0071 Fax: 708 285-0075

Dallas

Microchip Technology Inc. 14651 Dallas Parkway, Suite 816 Dallas, TX 75240-8809 Tel: 972 991-7177 Fax: 972 991-8588

Dayton

Microchip Technology Inc. Suite 150 Two Prestige Place Miamisburg, OH 45342 Tel: 513 291-1654 Fax: 513 291-9175

Los Angeles

Microchip Technology Inc. 18201 Von Karman, Suite 1090 Irvine, CA 92612 Tel: 714 263-1888 Fax: 714 263-1338

New York

Microchip Technmgy Inc. 150 Motor Parkway, Suite 416 Hauppauge, NY 11788 Tel: 516 273-5305 Fax: 516 273-5335

San Jose

Microchip Technology Inc. 2107 North First Street. Suite 590 San Jose, CA 95131 Tel: 408 436-7950 Fax: 408 436-7955

Toronto

Microchip Technology Inc. 5925 Airport Road, Suite 200 Mississauga, Ontario L4V 1W1, Canada Tel: 905 405-6279 Fax: 905 405-6253

ASIA/PACIFIC

China

Microchip Technology Unit 406 of Shanghai Golden Bridge Bldg. 2077 Yan'an Road West, Hongiao District Shanghai, Peoples Republic of China Tel: 86 21 6275 5700 Fax: 011 86 21 6275 5060

Hong Kong

Microchip Technology RM 3801B, Tower Two Metroplaza 223 Hing Fong Road Kwai Fong, N.T. Hong Kong Tel: 852 2 401 1200 Fax: 852 2 401 3431 India Microchip Technology No. 6, Legacy, Convent Road Bangalore 560 025 India Tel: 91 80 526 3148 Fax: 91 80 559 9840 Korea **Microchip Technology** 168-1, Youngbo Bldg. 3 Floor Samsung-Dong, Kangnam-Ku, Seoul, Korea Tel: 82 2 554 7200 Fax: 82 2 558 5934 Singapore Microchip Technology 200 Middle Road #10-03 Prime Centre Singapore 188980 Tel: 65 334 8870 Fax: 65 334 8850 Taiwan, R.O.C Microchip Technology

10F-1C 207 Tung Hua North Road Taipei, Taiwan, ROC Tel: 886 2 717 7175 Fax: 886 2 545 0139

EUROPE

United Kingdom

Arizona Microchip Technology Ltd. Unit 6, The Courtyard Meadow Bank, Furlong Road Bourne End, Buckinghamshire SL8 5AJ Tel: 44 1628 850303 Fax: 44 1628 850178 France Arizona Microchip Technology SARL Zone Industrielle de la Bonde

2 Rue du Buisson aux Fraises

91300 Massy - France Tel: 33 1 69 53 63 20 Fax: 33 1 69 30 90 79 Germany

Arizona Microchip Technology GmbH Gustav-Heinemann-Ring 125 D-81739 Muenchen, Germany Tel: 49 89 627 144 0 Fax: 49 89 627 144 44

Italy

Arizona Microchip Technology SRL Centro Direzionale Colleone Pas Taurus 1 Viale Colleoni 1 20041 Agrate Brianza Milan Italy Tel: 39 39 6899939 Fax: 39 39 689 9883

JAPAN

Microchip Technology Intl. Inc. Benex S-1 6F 3-18-20, Shin Yokohama Kohoku-Ku, Yokohama Kanagawa 222 Japan Tel: 81 45 471 6166 Fax: 81 45 471 6122

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